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February 2011

FAN3989 USB/Charger Detection Device with Load Switch

Features

- Charger/USB Detection Device with Load Switch
- Charger/USB Device Detection Flag
- Over/Under-Voltage Detection Flag
- Load Switch Output, Up to 1.5A Charge Current
- V_{BUS} Supply: 2.7V to 20V
- C_{ON}: 1.5pF
- Package: 8-Lead MLP

Applications

- Mobile Phones
- Handheld Devices

Related Resources

 AN-5067 — PCB Land Pattern Design and Surface Mount Guidelines for MLP Packages

Description

The FAN3989 is a USB connection monitoring device used to determine if a standard USB device is connected or a battery-charging device is connected.

The FAN3989 sets the FLAG1 pin to logic HIGH or LOW as an indicator to the system controller that a standard USB device or a charger is connected to the USB port. The FAN3989 also monitors the V_{BUS} for over- or undervoltage conditions. The FLAG2 pin is set LOW if V_{BUS} is less than 3.3V or greater than 6.0V. The internal load switch control pin is set HIGH if V_{BUS} is less than 3.3V or greater than 6.0V, turning off the PMOS switch.

The FAN3989 is available in a very small 8-lead MLP package suitable for small board space applications, like mobile phones.

Ordering Information

Part Number	Operating Temperature Range	Package	Packing Method	Quantity
FAN3989MLP8X	-40°C to +85°C	8-Lead Molded Leadless Package (MLP)	Reel	3000

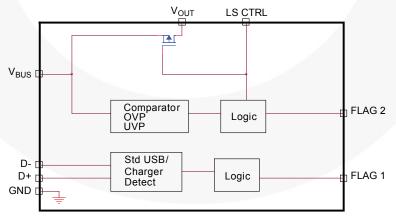
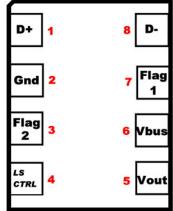


Figure 1. Block Diagram

Pin Configuration





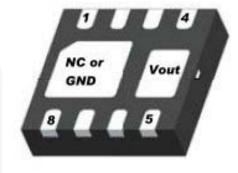


Figure 3. Pin Configuration (Bottom View)

Pin Definitions

Pin#	Name	Туре	Description
1	D+	Input	USB Data Input
2	GND	Input	Device Ground
3	Flag2	Output	Over-/Under-Voltage Flag Output
4	LSCTRL	Output	PMOS Switch Control – Pull-Up Connection to V _{BUS}
5	V _{OUT}	Output	Voltage Out – Connection also on Package DAP (see PCB Layout Guideline section)
6	V _{BUS}	Input	Power Input from Charger, USB Device, or Handheld Battery
7	Flag1	Output	Charger / Standard USB Device Detect Flag
8	D-	Input	USB Data Input

Truth Table

Connection State	V _{BUS}	D-	D+	FLAG1	FLAG2	LS CTRL	Description
STD USB Device	0V	R to GND	R to VDD	LOW	LOW	HIGH	Load switch open
STD USB Device	5V	R to GND	R to VDD	LOW	HIGH	LOW	Load switch closed
USB Charger	5V	Short to D+	Short to D-	HIGH	HIGH	LOW	Normal state, load switch closed
V _{BUS} GT 6V	GT 6V	Short to D+	Short to D-	HIGH	LOW	HIGH	Load switch open
V _{BUS} LT 3.3V	LT 3.3V	Short to D+	Short to D-	HIGH	LOW	HIGH	Load switch open
PC Charger	5V	Open	Open	LOW	HIGH	LOW	Load switch closed

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
Vs	DC Supply Voltage	-0.3	20.0	V
V_{IO}	Analog and Digital I/O	-0.3	V _{CC} +0.3	V

Reliability Information

Symbol	Parameter	Min.	Тур.	Max.	Unit
T _J	Junction Temperature			+150	°C
T _{STG}	Storage Temperature Range	-65		+150	°C
Θ_{JA}	Thermal Resistance, JEDEC Standard, Multilayer Test Boards, Still Air		41		°C/W

Electrostatic Discharge Information

Symbol	Parameter	Max.	Unit
Human Body Model, JESD22-A114		3	14) /
ESD Charged Device Model, JESD22-C101		1	kV

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

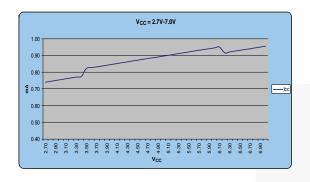
Symbol	Parameter	Min.	Тур.	Max.	Unit
T _A	Operating Temperature Range	-40		+85	°C
V _{CC}	Supply Voltage Range	2.7	5.0	20.0	V

DC Electrical Characteristics

 T_A = 25°C, V_{CC} = 5.0V, unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units		
Supply	Supply							
Vs	Supply Voltage Range	V _S Range	2.7	5.0	20.0	V		
I _{CC}	Quiescent Supply Current	V_S = +5.0V, D+ D- Shorted		1.2	2.0	mA		
t _{SUPPLY}	Power-Up Stabilization Time	V_S = +5.0V, D+ D- Shorted		10		ms		
Input Charac	cteristics							
C _{D+}	Input Capacitance			1.5	2.0	pF		
C _{D-}	Input Capacitance			1.5	2.0	pF		
I _{off} D+	Off Leakage Current	V_{BUS} = 0V or 5V V_{IN} on D+ = 5V		1		μA		
I _{off} D-	Off Leakage Current	V_{BUS} = 0V or 5V V_{IN} on D- = 5V		1		μA		
Output Char	acteristics							
OV _{DETECT}	Over-Voltage Threshold Detect	V _S = +5.0V, Flag2 = LOW	5.8	6.2	6.5	V		
OV _{HYST}	Over-Voltage Hysteresis	Voltage Sweep through Upper and Lower Trip Points		100		mV		
UV _{DETECT}	Under-Voltage Threshold Detect	V _S = +5.0V, Flag2 = LOW	3.0	3.3	3.6	V		
UV _{HYST}	Under-Voltage Hysteresis	Voltage Sweep through Upper and Lower Trip Points		100		mV		
V _{OH} FLAG1/ FLAG2	Minimum HIGH Output Voltage	V _S = +5.0V, I _{OH} = -20μA	2.4			V		
V _{OL} FLAG1/ FLAG2	Maximum LOW Output Voltage	V _S = +5.0V, I _{OL} = 20μA			0.3	V		
V _{OL} LS_CTRL	Maximum LOW Output Voltage	V _S = +5.0V, I _{OL} = 100μA			0.3	V		
VB _{DSS}	Drain Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu A$	-20			V		
R _{DSON}	Static Drain-Source On Resistance	V _{GS} = -5.0V, I _P = 1A		186		mΩ		
C _{iss}	Input Capacitance	V 40V V 0V 5 4 0MI		330		pF		
C _{oss}	Output Capacitance	$V_{DS} = -10V, V_{GS} = 0V, f = 1.0MHz$	/.	80		pF		
t _{d(on)}	PMOS Turn-On Delay Time	$V_{DD} = -5V, I_P = -0.5A,$		5		μs		
t _{d(off)}	PMOS Turn-Off Delay Time	$V_{GS} = -4.5V$, $R_{GEN} = 6\Omega$		14		μs		

Typical Performance Characteristics



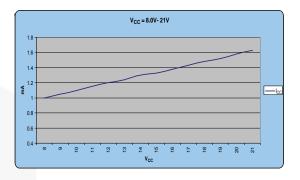


Figure 4. I_{CC} vs. V_{CC} (2.7V-7.0V) No Load

Figure 5. I_{CC} vs. V_{CC} (8.0V-21V) No Load

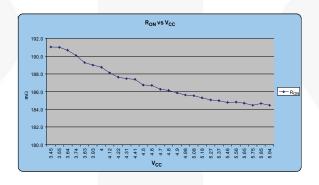


Figure 6. R_{ON} vs. V_{CC} (10 Ω Load)

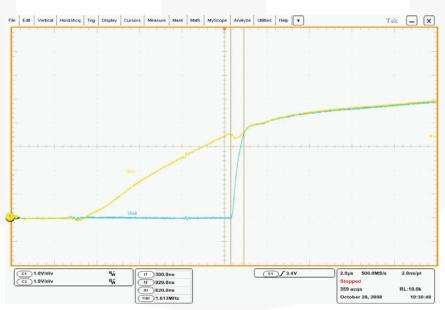


Figure 7. Turn-On Time

Typical Performance Characteristics (Continued)

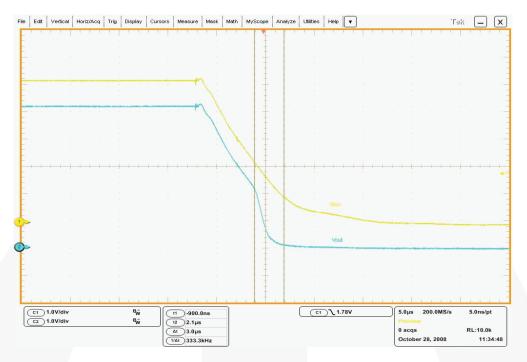


Figure 8. Turn-Off Time

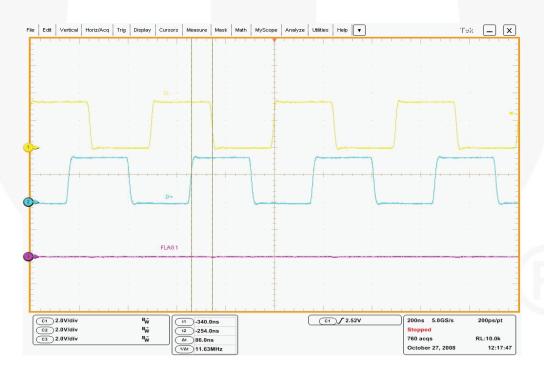


Figure 9. No Fault on Flag 1, Skew=65ns



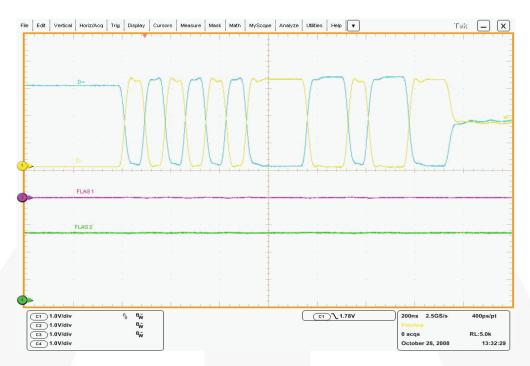


Figure 10. PC Data Running D+/D- (Flag 1 and Flag 2 at Correct Levels)

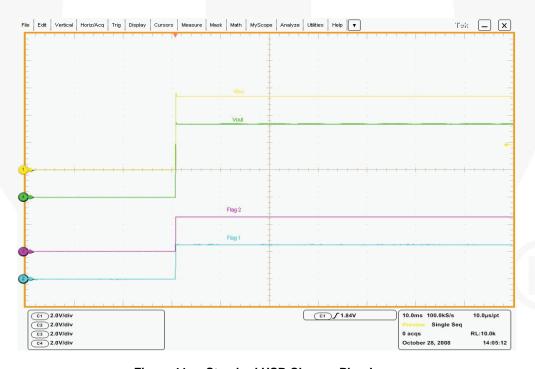


Figure 11. Standard USB Charger Plug-In

Applications Information

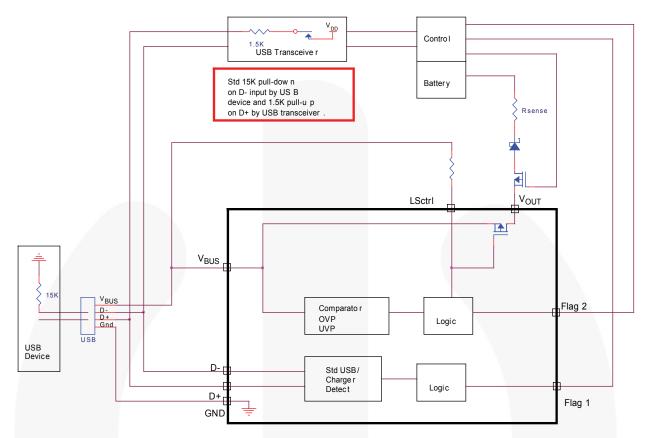


Figure 12. Mobile Phone Battery Charging System with USB Interface

The FAN3989 sets the FLAG1 pin to logic HIGH or LOW as an indicator to the system controller that a standard USB device or a charger is connected to the USB port. The FAN3989 also monitors the V_{BUS} for over- or under-voltage conditions. If V_{BUS} is less than 3.3V or greater than 6.0V, the FLAG2 pin is set LOW and the internal load switch control pin is set HIGH, turning off the PMOS switch.

In a standard USB configuration, there is a switch in the USB transceiver that is always on in full-speed mode. It is on during the transition from full-speed to high-speed mode and turned off after enumeration is complete. If D+ and D- are shorted when a charger is plugged into the USB port, the USB switch is on and pulled to $V_{\text{DD}},$ which is about 3V, making both D+ and D- HIGH. Flag1 is also set HIGH, indicating that a charging device is connected to the port. If D+ and D-are connected to a standard USB device, the D+ is pulled to V_{DD} and D- is set low (due to the 15K Ω pull-down resistor on the USB device) and flag1 is LOW. If D+ and D- are open (floating), D+ is pulled to V_{DD} and D- floats LOW, which makes flag1 LOW.

Applications Information (Continued)

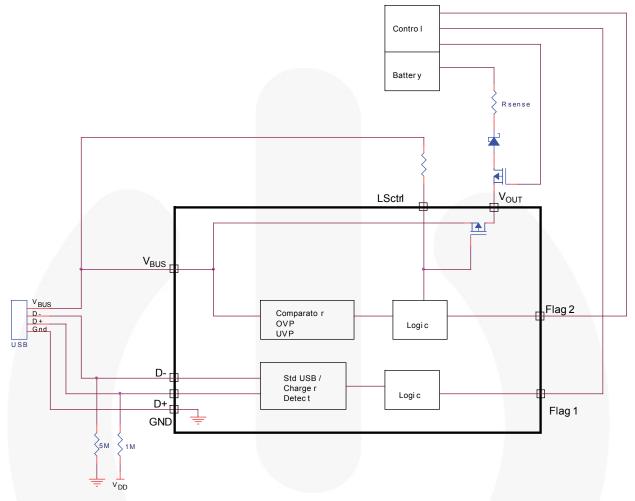


Figure 13. Mobile Phone Battery Charging System without USB Interface

The FAN3989 sets the FLAG1 pin to logic HIGH or LOW as an indicator to the system controller that a standard USB device or a charger is connected to the USB port. The FAN3989 also monitors the V_{BUS} for over- or under-voltage conditions. If V_{BUS} is less than 3.3V or greater than 6.0V, the FLAG2 pin is set LOW and the internal load switch control pin is set HIGH, turning off the PMOS switch.

Where a USB transceiver is not incorporated or there is a switch between the USB port and the FAN3989, external resistors are used to set the correct input logic states on the D+ and D- inputs. A 5M Ω pull-down on the D- line and a 1M Ω pull-up to V_{DD} on the D+ line are recommended. If a charger is plugged into

the USB port (D+ and D- shorted), the voltage divider of 1M and 5M put a voltage of 2.3V on the D+D-inputs and flag1 is HIGH, indicating a charger is connected to port.

If the USB port is connected to a standard USB device, the D+ input is pulled up to V_{DD} and is in parallel with the $1.5 K\Omega$ on a USB transceiver with a parallel R value of $1.497 K\Omega.$ The D- input is connected to a $15 K\Omega$ pull-down by the USB device and in parallel with $5 M\Omega$ with a parallel R value of $14.955 K\Omega.$ This condition forces flag1 LOW. If D+ and D- are open (floating), D+ is pulled to V_{DD} and D-floats LOW, which forces flag1 LOW.

PCB Layout Guidelines

Please also see Fairchild Semiconductor applications note AN-5067 — PCB Land Pattern Design and Surface Mount Guidelines for MLP Packages

Pad1

This exposed DAP is connected to the internal FET drain and labeled V_{OUT} on the device. The pad should be connected to V_{OUT} pin of the device or left floating. It

should never be connected to the ground, power plane, or Pad2.

Pad2

This exposed DAP is connected to an internal die substrate that is at a ground potential. The pad should be left floating or can be connected to ground plane. This pad should never be connected to Pad1 or the power plane.

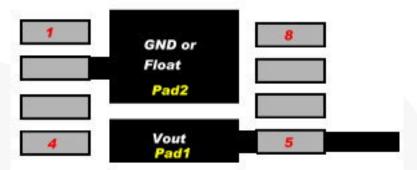
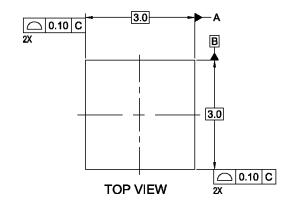
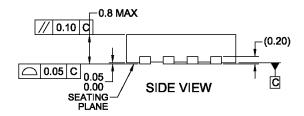
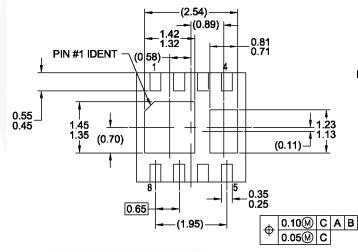


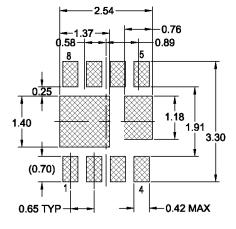
Figure 14. PCD / Pad Layout

Physical Dimensions









RECOMMENDED LAND PATTERN (NSMD PAD TYPE)

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-229, VARIATION VEEC, DATED 11/2001
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- D. LAND PATTERN RECOMMENDATION IS BASED ON FSC DESIGN ONLY
- E. DRAWING FILENAME: MKT-MLP08Erev2.

Figure 15. 8-Lead Molded Leadless Package (MLP)

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